

EAST: (10825910 heatsink between chips.wsp:1)

File View Edit Layout Window Help

12: (61) 6472741 "5600541" 200408562771.pn.

13: (12) Backward citation search 1

14: (45) Forward citation search 1

15: (262561) heatsink (heat thermal\$2) near (sink\$4 spread\$3 dissipat

16: (56781) undercut under adj cut

17: (105) 15 with 16

18: (84040) t near shap\$4

19: (481492) interpos\$4

110: (110) 5 near 4 8

111: (85808) notched

112: (459271) (undercut under adj) cut t near shap\$4 notch

113: (816788) 5 8

114: (12059) 19 near 9 12

115: (513424) (undercut under adj) cut t near shap\$4 notch\$4

116: (12061) 19 near 9 15

117: (79554) wir\$4 near bond\$4

118: (17) 16 same 17

119: (136) 16 and 17

120: (4) "6368455".pn. "6851028".pn.

121: (13) Backward citation search 2

122: (8) Forward citation search 2

123: (8) Forward citation search 3

124: (0) Forward citation search 4

125: (9) Backward citation search 3

126: (57) Forward citation search 5

Called

June 2005

Current Current X Retrieval S C P

U	I	Inventor	Document	Issued	P	Title	Current	Current X	Retrieval	S	C	P	Image	Doc	P
1		Zhao; Sam Z	US 6887741	2005	5	Method for making an enhanced die-u	438/12							US 688774	
2		Zhao; Sam Z	US 688204	2005	2	Thermally and electrically enhanced b	257/70	257/712;						US 68820	
3		Cheah; Eng	US 688204	2005	8	Thermally enhanced metal capped B0	257/70	257/667;						US 68820	
4		Khan; Reza	US 687903	2005	2	Ball grid array package substrates and	257/73	257/678;						US 687903	
5		Zhao; Sam Z	US 687655	2005	6	Enhanced die-up ball grid array packa	381/76	381/784						US 687655	
6		Zhao; Sam Z	US 6861750	2005	3	Ball grid array package with multiple l	257/73	257/688;						US 686175	
7		Khan; Reza	US 685307	2005	2	Die-down ball grid array package with	257/707	257/771;						US 685307	
8		Chan; Vince	US 684894	2005	11	Integrated circuit package for the tran	257/70	257/675;						US 684894	
9		Khan; Reza	US 682510	2004	12	Ball grid array package fabrication wit	438/61	257/734;						US 682510	
10		Yonemochi	US 6818478	2004	11	Insert-moldable heat spreader, semic	438/12	257/623.0						US 681847	

U. N. C. P. A. B. S. H. T. C.

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